

977, 977Ls

Wafer Cleaner

Streamlined and effective cleaning solutions to bolster your operations. The ADT 977 Wafer Cleaner Systems are meticulously crafted for the purpose of cleaning workpieces subsequent to the dicing process.

Equipped with adjustable rotating cleaning arm with atomizing or high-pressure cleaning nozzles to cope with a wide range of cleanliness requirements.



Effective Cleaning Methods

The unit is equipped with a spinning chuck table and a rotating cleaning arm. It can be configured with Atomizing Cleaning Nozzle or High-pressure Nozzle, providing a comprehensive cleaning solution to a wide range of workpiece types.

Easy Operation

ADT 977 is user-friendly. An intuitive display control allows the user to set the desired cleaning sequences, spinning velocity, and duration. Up to 20 with 20 cleaning steps recipes can be stored to match the specific requirements of each workpiece.

The unit supports real-time performance, monitoring and displaying status, total process time, and alarms during operation.

Wide Range Of Workpieces

Two basic models are available: **ADT 977** supports up to 8" diameter workpieces, and **ADT 977 Ls** supports up to 12"x12" square or 12" diameter workpieces. A variety of chuck tables and frames can be configured.

System Highlights

- Compact design
- Atomizing and High-pressure cleaning
- Easy to use one-touch activation with automatic lead cover closing
- Intuitive operating panel
- Process monitoring through status and alarm displays
- Light tower and buzzer
- Compliance with stringent safety standards
- Environment friendly

977, 977Ls Wafer Cleaners - The ideal choice for single frame processing!











977, 977-LS Wafer Cleaner

Features & Benefits

- · Atomizing cleaning
- · Air and nitrogen separation
- · Nitrogen and water adjustable pressure gages
- · Internal vacuum generator to hold the workpiece
- Air puff release
- · Robust, vibration-free
- · Safety interlock
- · Automatic covering/opening

Options

- · Chucks: Ceramic 5", 6", 8", 12" Grip rings Unmounted wafers
- Mist suction
- Ionizer elimination of static charge
- · Cleaning additives
- High-pressure pump
- CO₂ injection
- · Water resistivity monitoring



Specifications	97	7 977Ls	
Max. workpiece size	Ø 200 mm (8")	Ø 12" or 12"x12" square	
Cleaning Method	Atomizing / High-pressure cleaning		
Number of recipes that can be saved	20 recipes with 20 cleaning steps		
Spinner velocity range	200-3,000 rpm	200-2,000 rpm	
Utility requirements:			
Power supply	208-230 Vac 50/60 Hz, single phase		
Power consumption during cleaning	300 Watt, during standby - 50 Watt		
Air/Nitrogen pressure	4-5 bar		
Max water flow	1,000 mL/min		
Water pressure	3-5 bar		
Exhaust	150 CFM		

Dimensions and weight

Dimensions (WxDxH)	410 x 625 x 964 mm	570 x1250 x 1073 mm	5
Weight	120 Kg	200 Kg	7















